TENTATIVE TOSHIBA INSULATED GATE BIPOLAR TRANSISTOR SILICON N CHANNEL IGBT

GT10Q311

HIGH POWER SWITCHING APPLICATIONS

MOTOR CONTROL APPLICATIONS

The 3rd Generation

Enhancement-Mode

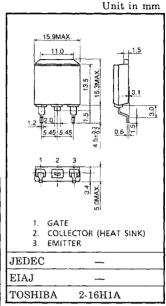
High Speed : $t_f = 0.40 \mu s$ (Max.)

Low Saturation Voltage: VCE (sat) = 3.5V (Max.)

FRD included between Emitter and Collector

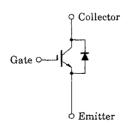
MAXIMUM RATINGS (Ta ≈ 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Collector-Emitter Voltage		VCES	1200	V	
Gate-Emitter Voltage	v_{GES}	±20	v		
Collector Current	DC	$I_{\mathbf{C}}$	10	Α	
Collector Current	1ms	ICP	20	A	
Emitter-Collector	DC	$I_{\mathbf{F}}$	10	Α	
Forward Current	1ms	I_{FM}	20	A	
Collector Power Dissipation (Tc=25°C)		PC	130	w	
Junction Temperature	T_j	150	°C		
Storage Temperature Ra	$\mathrm{T_{stg}}$	-55~150	°C		



Weight: 3.65g

EQUIVALENT CIRCUIT



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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		IGES	$V_{GE} = \pm 20V, V_{CE} = 0$			±500	nA
Collector Cut-Off Current		ICES	$V_{CE} = 1200V, V_{GE} = 0$	_		1.0	mA
Gate-Emitter Cut-Off Voltage		V _{GE} (OFF)	$I_{\rm C}=1{\rm mA},\ V_{\rm CE}=5{\rm V}$	5.0		8.0	V
Collector-Emi Voltage	tter Saturation	V _{CE} (sat)	$I_{C} = 10A, V_{GE} = 15V$	_	2.7	3.5	v
Input Capacitance		Cies	$V_{CE}=10V$, $V_{GE}=0$, $f=1MHz$		1800		pF
Switching Time	Rise Time	tr	Inductive Load		0.30		μs
	Turn-On Time	ton	$V_{CC} = 600 \text{ V}, I_{C} = 10 \text{ A}$ $V_{GE} = \pm 15 \text{ V}, R_{G} = 120 \Omega$	_	0.40	T —	
	Fall Time	tf		_	0.20	0.40	
	Turn-Off Time	toff	(Note)	-	0.70		
Peak Forward	i Voltage	$V_{\mathbf{F}}$	$I_F = 10A$, $V_{GE} = 0$	T-		3.0	V
Reverse Recovery Time		trr	$I_F = 10A$, di/dt = $-100A/\mu s$			300	ns
Thermal Resistance (IGBT)		Rth (j-c)			_	0.96	°C/W
Thermal Resistance (Diode) R _t		Rth (j-c)	_	_	T-	3.68	°C/W

(Note) Switching time measurement circuit and input/output waveforms

